

INFORMATION NOTE



N° 029/18

Dear Customer,

With this INFINEON Technologies Information Note we would like to inform you about the following

Harmonization of Easy packaging

Infineon Technologies AG
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N° 029/18

Harmonization of Easy packaging

► **Products affected:** All Easy solder pin modules

► **Detailed Change Information:**

Subject: • Elimination of desiccant bag (silica bag) in packaging of solder pin modules

Reason: • Harmonization with packaging process of Easy PressFIT modules, that also do not include desiccant bag (silica bag)

Description:	<u>Old</u>	<u>New</u>
	■ Packaging of Easy solder pin modules includes a desiccant bag (silica bag)	■ Packaging of Easy solder pin modules will no longer include a desiccant bag (silica bag)

► **Product Identification:** Pocket for desiccant bag (silica bag) in packaging is empty

► **Impact of Change:** The specifications of the mentioned modules, like electrical- and mechanical parameters, remain unchanged according to JEDEC Standard JESD46-C: form, fit, function and reliability.
Desiccant bag (silica bag) technically not needed

► **Attachments:** N.A.

► **Intended start of delivery:** Planned implementation: Deliveries from July 2018 onwards.
During transition period deliveries with/without desiccant bag will be possible.

If you have any questions, please do not hesitate to contact your local Sales office.